



Customer Information Notification

201906029I

Issue Date: 29-Jun-2019

Effective Date: 29-Jul-2019

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.



QUALITY

Change Category

Wafer Fab Process

Wafer Fab Materials

Wafer Fab Location

Firmware

Assembly Process

Assembly Materials

Assembly Location

Other

Product Marking

Mechanical Specification

Packing/Shipping/Labeling Equipment

Test Location

Test Process

Test Equipment

Design

Errata

Electrical spec./Test coverage

MPC5777C Site Expansion: Burn-In from KESM Kuala Lumpur to KESM Tianjin and Final Test from NXP-ATKL to NXP-ATTJ

Description

NXP Semiconductors announces the site expansion for the MPC5777C products (maskset 3N45H) associated with this notification:

1. Burn-in site expansion from the current KESM Kuala Lumpur, Malaysia Burn-in site to the KESM Tianjin, China Burn-in site. Packages covered by the burn in site expansion are the 516MAPBGA and 416MAPBGA.
2. Final test site expansion from the current NXP-ATKL, Kuala Lumpur, Malaysia Final Test site to the NXP-ATTJ, Tianjin, China Final Test site. Packages covered by the final test site expansion are the 516MAPBGA and 416MAPBGA.

Site expansion was successfully qualified adhering to NXP specifications.
Corresponding ZVEI Delta Qualification Matrix ID: SEM-TF-01

Please see the attached file(s) for additional details.

Reason

Site expansion qualification is required for manufacturing flexibility and customer supply assurance.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Burn-in and final test site expansion. No depletion of inventory required.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP](#) | [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.

Affected Part Numbers

SPC5777CCK3MME3

SPC5777CK3MMO3

SPC5777CK3MME3

SPC5775BDK3MME2

SPC5777CDK3MMO3

SPC5777CDK3MME4

SPC5777CDK3MMO4

SPC5775EDK3MME3

SPC5777CDK3MME3